



SDM1U30CP3

1A SCHOTTKY BARRIER RECTIFIER DIE SIZE SURFACE MOUNTED PACKAGE

Product Summary

V _{RRM} (V)	I _O (A)	V _F Max (mV)	I _R Max (μA) @ 20V
30	1	500	150

Description and Applications

The SDM1U30CP3 is a 30V 1A Schottky barrier rectifier that is optimized for very low forward voltage drop and low leakage current, housed in a compact die size surface mounted package that occupies only 0.6mm² board-space. The low thermal resistance enables designers to meet design challenges of increasing efficiency while at the same time reducing board space. It is ideally suited for use in portable applications such as:

- Blocking Diode
- Boost Diode

Notes:

- Switching Diode
- Reverse Protection Diode

Features and Benefits

- Offboard Profile of 0.275mm—More han 30% Thinner Than DFN1006
- Very Low Forward Voltage (V_F) Minimizes Conduction Losses and Improves Efficiency
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: X3-DSN1006-2
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method 208 @
- Polarity: Cathode Dot
- Weight: 0.001 grams (Approximate)

Ordering Information (Note 4)

Part Number	Case	Packaging
SDM1U30CP3-7	X3-DSN1006-2	5000/Reel

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

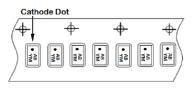
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



XG = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: E = 2017) M = Month (ex: 9 = September) Dot Denotes Cathode Pin



Date Code Key

Year	201	6	2017		2018	20	19	2020		2021	2	2022
Code	D		E		F	(3	Н				J
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code		•	0	4	-	0	-	0	•	0	N	5



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Average Rectified Output Current	Ι _Ο	1	А
Repetitive Peak Forward Current (Pulse Wave = 1ms, Duty Cycle = 25%)	I _{FRM}	4	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	10	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{0JA}	165	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	R _{0JA}	70	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

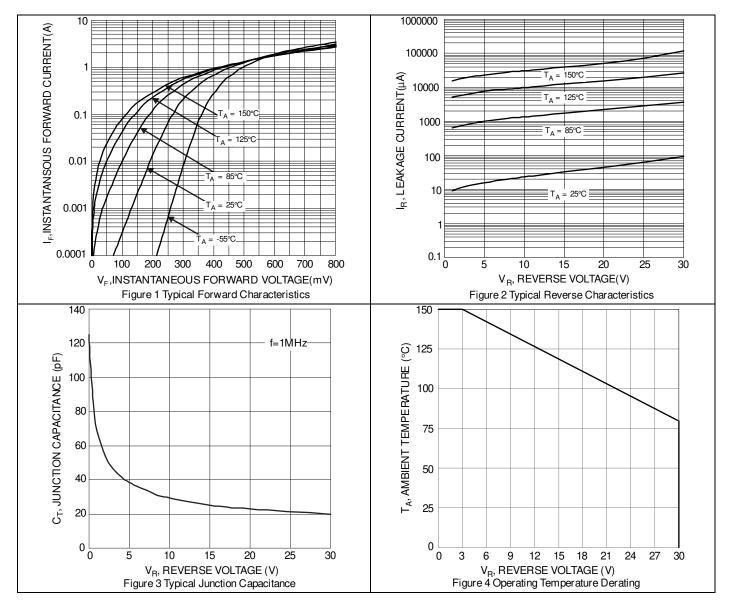
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage	V(BR)	30	—	—	V	IR=1mA
Forward Voltage Drop	V	—	267	325	mV	$I_F = 0.1A, T_J = +25^{\circ}C$
	V _F	—	455	500		$I_F = 1.0A, T_J = +25^{\circ}C$
eakage Current (Note 7)	1-	R —	45	150	μA	$V{R} = 20V, T_{J} = +25^{\circ}C$
Leakage Current (Note 7)	IR		95	350 ^{µA}	$V_{R} = 30V, T_{J} = +25^{\circ}C$	
Junction Capacitance	Ст		69	pF	f = 1.0MHz, V _R = 1V	
	UI UI		29		р	f = 1.0MHz, V _R = 10V

Notes:

Device mounted on FR-4 PCB, 2oz. Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.
Device mounted on FR-4 PCB, 2oz. 1 square inch Copper.
Short duration pulse test used to minimize self-heating effect.



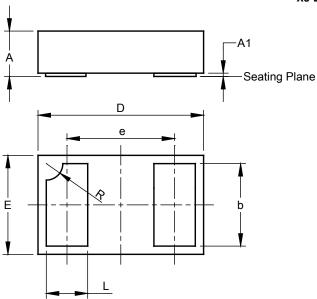
SDM1U30CP3





Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

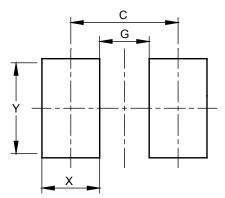


X3-DSN1006-2						
Dim	Min	Max	Тур			
Α	0.25	0.30	0.275			
A1	0.00	0.02				
b	0.48	0.52	0.50			
D	0.95	1.05	1.00			
E	0.55	0.65	0.60			
е			0.65			
L	0.23	0.27	0.25			
R			0.10			
All	Dimensi	ions in	mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-DSN1006-2



Dimensions	Value (in mm)
С	0.65
G	0.30
Х	0.35
Y	0.60

X3-DSN1006-2



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